



Final Product Change Notification

202303021F01 : Second Source Leadframe for Selected QFN Packages at NXP Assembly Site Kaohsiung (ATKH)

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 14, 2023 **Effective date:** Sep 12, 2023

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to [view this notification online](#)

Management summary

NXP announces a second source lead frame supplier for the devices from ATKH listed in this notification. The NiPdAu plating thickness of the second source differs slightly compared to the current first source.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP introduces a second source lead frame supplier for the devices manufactured in assembly site Kaohsiung and listed in this notification.

There is no change to the package case outline, materials, or design, however the NiPdAu plating thickness of the second source differs slightly compared to the current first source.

Both lead frame types are standard and widely used in large volume across NXP products.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-05

Please see the attached qualification report for additional details.

Reason

Qualification of alternative lead frame supplier is required for manufacturing flexibility as assurance of future supply chain continuity.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Sep 12, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

With the exception of slight difference to NiPdAu plating thickness of the 2nd source, no other impact to form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Products with both first and second source leadframe will be shipped in parallel.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 14, 2023.

Remarks

A ZVEI Delta Qualification Matrix (DeQuMa) is attached both zipped in pdf and excel format. For customers with corresponding agreements, feedback time to notification and date of first shipment will be aligned accordingly.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Michiel Maas Geesteranus
Position Technical Change Coordinator
e-mail address michiel.maas.geesteranus@nxp.com

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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